







DISCRIPTION

FEATURES

Ceramic Core
High frequency design
Excellent Q values
Excellent SRF
High reliability
Excellent thermal stability

OPTIONS

Tape & Reel is Standard (Qty: 3.000 Pcs)
Bulk Packing Available for smaller quantites
Tolerance: J = 5% and K=10% is Standard,
tighter Tolerance available (MOQ on request)

APPLICATIONS

Modems
Mobile Radios
Cordless Telephones
Global Positioning Systems
Telecommunications Systems

PHYSICAL CHARACTERISTICS

• Testing: (Equivalents acceptable) Inductance & Q-HP4191A + HP41951

SRF: HP8753B; RDC: 25°C

Operating Temperature : Ceramic -55°C ~ 125°C
 Pad metalization : Tungsten-nickel with gold flash
 Solder methods : Wave, Reflow, Vapor Phase
 Solderability : Max 260°C for 10 seconds

• Marking : EIA color code

ELECTRICAL SPECIFICATIONS

Properties	Test conditions		Value	Unit	Tol.
Inductance		L	620	nH	see Site 2
Q factor		Q	23		min.
DC-resistance		DCR typ.		Ω	typ.
DC-resistance		DCR max.	2,080	Ω	max.
Self-Res. Freq.		SRF	320	Mhz	min.
Test-Freq.			50	Mhz	
Rated Current		IDC	200	mA	max.
Saturation Current		Isat		mA	typ.

This electronic component is meant to be used in general electronic equipment. Before the incorporation of this component into any equipment with higher and more reliable requirements such as aviation, aerospace, submarine, nuclear control, transportation, transportation signal, disaster prevention, medical, public information network, etc. or if there is a possibility of injuries or damages to the human body, Edcon—Components must be informed before the stage of design-in. Evaluation checks for safety have to be performed on each electronic components used in electrical circuits that require high safety and reliability functions.

SMT WIRE-WOUND CERAMIC CHIP INDUCTORS

Part No.: **\$12003-R62**

Customer:

DRW: Chang CHKD Young MATL: Chu Chi DATE 09.06.2009
APPD: Pong FINISH Vienna Sheet 1 from 2

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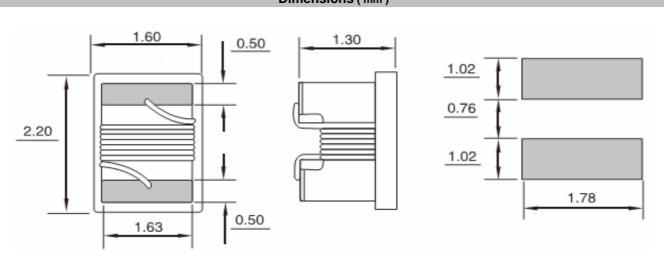






TECHNICAL INFORMATIONS

Dimensions (mm)



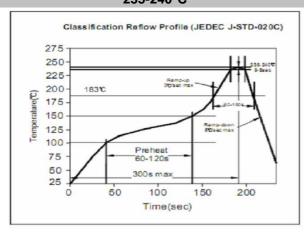
Ordering Information

Serie and Range
S12003-R62

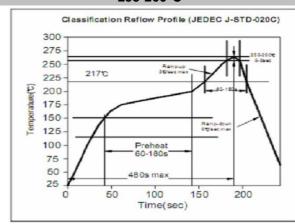
Tolerance	ROHS	Packing		
K	R	TR		

J = 5%	R = ROHS	BU = Bulk Ware		
K = 10%	N = non ROHS	TR = Tape Reel		
M = 20%				
N = 30%				

Soldering Profile for Lead Free Soldering 235-240°C



Soldering Profile for Lead Free Soldering 255-260°C



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